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Sheet 1 of 1

FORM PTO-1449 (Modified) INFORMATION DISCLOSURE STATEMENT BY APPLICANT (Use Several Sheets If Necessary) (37 CFR § 1.98(b))	U.S. Department of Commerce Patent and Trademark Office	007685/PMG/EPIC/JW Attorney Docket No.:	Serial No.: 10/654,240
	Applicant Judon Tony PAN:		
	Filing Date: 09/02/2003		Group: 2818

U.S. PATENT DOCUMENTS

Examiner Initials		Serial/Patent Number	Issue Date	Applicant/Patentee	Class	Subclass	Filing Date
Dle	AA	U.S. 09/553,461		Huang et al.			4/19/00
	AB	6,452,271 ✓	9/17/02	Jiang et al.	257	750	7/31/98
	AC	6,445,069 ✓	9/3/02	Ling et al.	257	738	1/22/01
	AD	6,444,489 ✓	9/3/02	Lin	438	107	12/15/00
	AE	2002/0096764	7/25/02	Huang			1/19/01
	AF	6,424,036 ✓	7/23/02	Okada	257	734	9/16/99
	AG	6,362,090 ✓	3/26/02	Paik et al.	438	614	11/3/00
	AH	2002/0005292	1/17/02	Kaneda et al.			7/2/01
	AI	2001/0033031	10/25/01	Shibata			3/22/01
	AJ	2001/0017221	8/30/01	Horiuchi et al.			2/24/01
	AK	2001/0013650	8/16/01	Goetz et al.			12/20/00
	AL	6,153,940	11/28/00	Zakel et al.	257	779	11/10/95
	AM	6,072,227	6/6/00	Yau et al.	257	642	7/13/98
	AN	6,054,379	4/25/00	Yau et al.	438	623	2/11/98
	AO	5,891,756	4/6/99	Erickson	438	108	6/27/97
	AP	5,886,877	2/23/99	Shingai et al.	361	768	10/9/96
	AQ	5,821,626	10/13/98	Ouchi et al.	257	778	6/25/96
	AR	5,290,732	3/1/94	Kumar et al.	437	183	6/9/92
	AS	5,192,835	3/9/93	Bull et al.	174	260	10/9/90
	AT	5,134,460	7/28/92	Brady et al.	357	71	11/2/90
	AU	4,661,375	4/28/87	Thomas	427	89	3/7/86
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OTHER DOCUMENTS (including Author, Title, Date, Relevant Pages, Place of Publication)

Dle	AW	Charles A. Harper, Ed., <u>Electronic Packaging And Interconnection Handbook</u> , 3 rd ed., McGraw-Hill, New York, pp. 7.87 & 7.88, 2000
	AX	George G. Harman et al., "Wire Bonding To Advanced Copper-Low-K Integrated Circuits, the Metal/Dielectric Stacks, and Materials Considerations", to be published in International Microelectronics Symposium (IMAPS), Baltimore, MD, 8 pages, Oct. 9-12, 2001

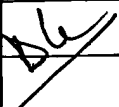
Examiner:

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Initial citation considered. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

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U.S. PATENT DOCUMENTS							
Examiner Initials	Serial/Patent Number	Issue Date	Applicant/Patentee	Class	Subclass	Filing Date	
	AA	6,570,243	5/27/03	Hagihara	257	620	11/21/00
	AB	6,468,894	10/22/02	Yang et al.	438	622	3/21/01

FOREIGN PATENT OR PUBLISHED FOREIGN PATENT APPLICATION							
Document Number	Publication Date	Country / Patent Office	Class	Subclass	Translation Yes No		

OTHER DOCUMENTS (including Author, Title, Date, Relevant Pages, Place of Publication)		

Examiner: 	Date Considered: 9/2005
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